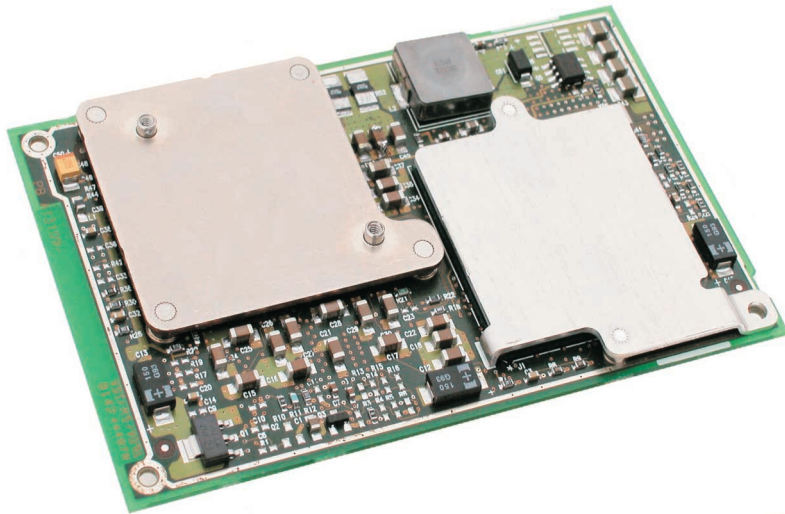
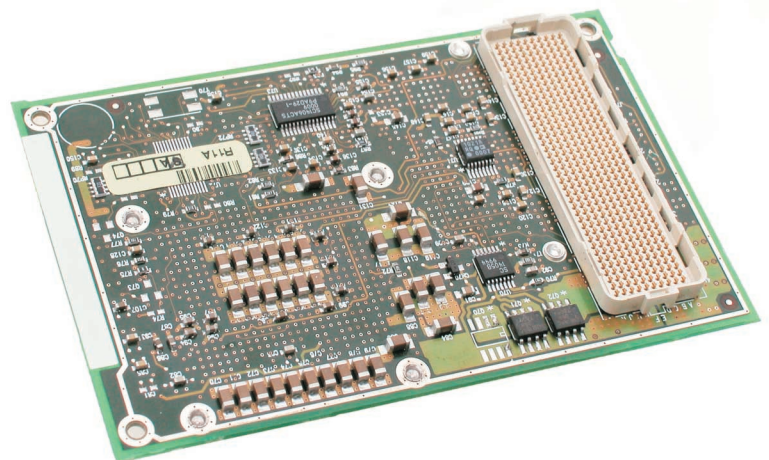


Low Power Module Mobile component



Kontron's MMC2 connector compatible CPU module leverages on your existing designs and extends the performance of your system.



Designed to be compatible with Intel's® MMC2 module, the Kontron Low Power Modules for Applied Computing are the driving force in embedded applications.

Kontron's module can extend the lifecycle of your existing designs based on the original 500MHz Intel PIII module with new CPU options.

With the 700 MHz Intel Pentium® III processor based module, Kontron's module leverages your design to extend the performance of your system in a low power envelope. In most applications, Kontron's modules enable customers to improve the performance of their system without redesigning it.

- ▶ Intel® Pentium® III at 500, 700 or 850 MHz
- ▶ Intel® 440BX or 440GX Hostbridge
- ▶ Enhanced 64-bit data bus
- ▶ AGP x 1 interface

Kontron's Low Power Module - Technical Specification

Processor

- Low Power Intel®, Pentium® III processor at 500 MHz
- Low Power Intel®, Pentium® III processor at 700 MHz
- Low Power Intel®, Pentium® III processor at 850 MHz with SpeedStep technology

Level 2 cache (internal)

- 256KB ECC 64-bit wide

Chipset

- Intel 440BX
- Optional 440GX (memory support of up to 1GB possible)

Memory

- Up to 512 MB SDRAM or EDO with ECC support

Buses

- 100MHz system bus, 66MHz AGP with sideband support 33MHz PCI

Power supply

- 5 V using approx. 15.0 W / 500MHz
- 5 V using approx. 14.0 W / 700MHz
- 5 V using approx. 20.0 W / 850MHz

Thermal Management

- Internal thermal diode in CPU accessible by I²C-Bus Programmable trip point

Power Management

- PCI Clock Run
- SDRAM clock enable
- Compatible SMRAM and Extended SMRAM mode
- SpeedStep-Support

Interface

- 400 pin BGA-type connector

Mounting

- Thermal transfer plate with two M2 crews for mounting customer cooling solution

Form Factor

- 2.5"H x 4"W x 0.39"D (63.5x101.6x9.9mm)

Temp./Humidity (operating)*

- 0°C to +55 °C / 5-90% @ 40 °C; non condensing (processor temp. from 0°C to 100°C as specified by Intel)

Temp./Humidity (storage)

- -40°C to +85 °C / 0-90% @ 40 °C; non condensing

Shock (non operating)

- 2G, 11ms duration(half-sine)

Shock (unpacked)

- 50G, 11ms duration (trapezoidal) 6-axis

Shock (Packaged)

- Inclined impact at 5.7 ft/s
- Half Sine, 2 ms at 36 inches simulated free fall

Vibration (unpacked)

- 5 Hz to 500 Hz, 2.2 g RMS random

Vibration (packaged)

- 10 Hz to 500 Hz, 1.0 g RMS
- 11,800 impacts 2 Hz to 5 Hz (low frequency)

ESD Damage Human Body Model

- The Module was tested at 2 KV and then inserted in a system for functional test.

EMC

- US: FCC CFR Part 15
- Europe: CISPR22 EN55081 EN55082

Safety

- CE
- Designed to meet UL

*Dependig on customers thermal solution

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